

1.0A HIGH VOLTAGE SCHOTTKY BARRIER RECTIFIER POWERDI®123

Features

- Guard Ring Die Construction for Transient Protection
- Low Power Loss, High Efficiency
- Patented Interlocking Clip Design for High Surge Current Capacity
- **Lead Free Finish, RoHS Compliant (Note 1)**
- **"Green" Molding Compound (No Br, Sb)**
- **Qualified to AEC-Q101 Standards for High Reliability**

Mechanical Data

- Case: POWERDI®123
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections: Cathode Band
- Terminals: Finish – Matte Tin annealed over Copper leadframe. Solderable per MIL-STD-202, Method 208 ③
- Weight: 0.01 grams (approximate)



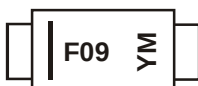
Top View

Ordering Information (Note 2)

Part Number	Case	Packaging
DFLS1100-7	POWERDI®123	3000/Tape & Reel

Notes: 1. EU Directive 2002/95/EC (RoHS). All applicable RoHS exemptions applied, see EU Directive 2002/95/EC Annex Notes
2. For packaging details, go to our website at <http://www.diodes.com>.

Marking Information



F09 = Product Type Marking Code
YM = Date Code Marking
Y = Year (ex: T = 2006)
M = Month (ex: 9 = September)

Date Code Key

Year	2004	2005	2006	2007	2008	2009	2010	2011	2012
Code	R	S	T	U	V	W	X	Y	Z

Month	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

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DFLS1100

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Maximum Ratings @T_A = 25°C unless otherwise specified

Single phase, half wave, 60Hz, resistive or inductive load.
For capacitance load, derate current by 20%.

Characteristic	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V _{RRM} V _{RWM} V _R	100	V
RMS Reverse Voltage	V _{R(RMS)}	71	V
Forward current rms (T _C = 160°C, D = 0.5)	I _{F(RMS)}	2	A
Average Forward Current	I _{F(AV)}	1.0	A
Non-Repetitive Peak Forward Surge Current 8.3ms Single Half Sine-Wave Superimposed on Rated Load	I _{FSM}	50	A
Repetitive peak reverse current tp = 2μs, f = 1 kHz square	I _{RRM}	1.0	A
Repetitive Peak Avalanche Power tp = 1μs, T _J = 25°C	P _{ARM}	1500	W
Non-repetitive peak reverse current tp = 100μs square	I _{RSM}	1.0	A
Critical rate of rise of reverse voltage (rated V _R , T _J = 25 °C)	dV/dt	10000	V/μs

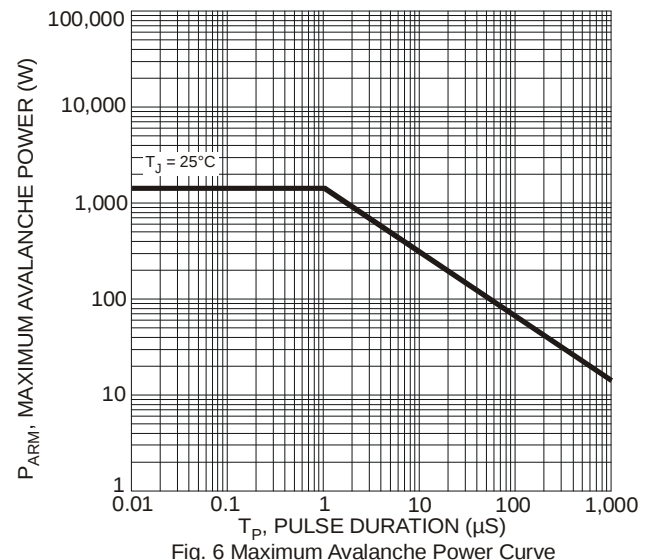
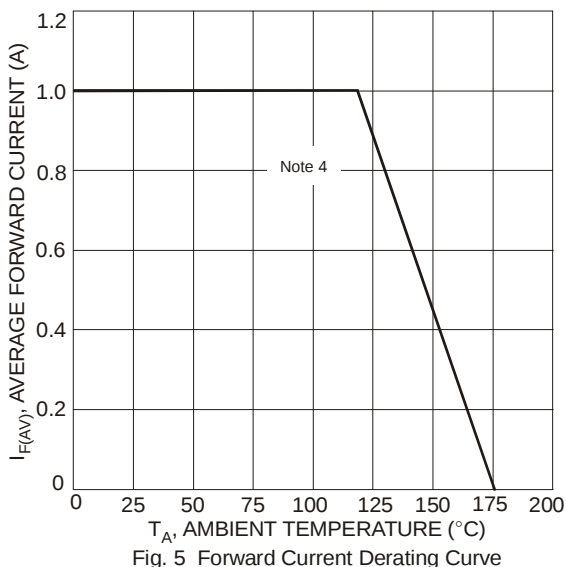
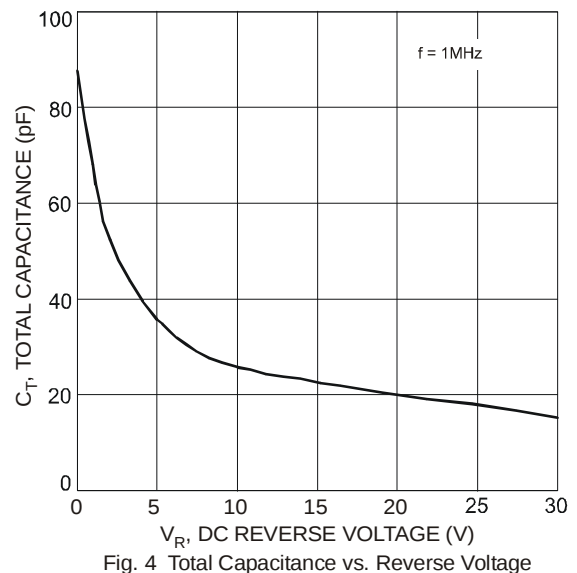
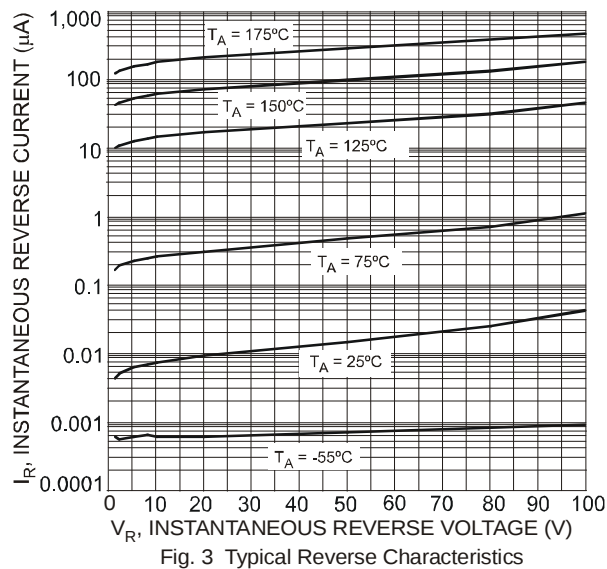
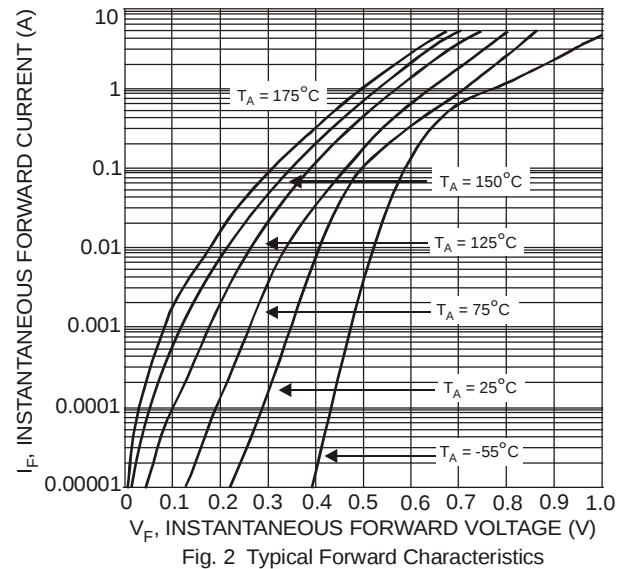
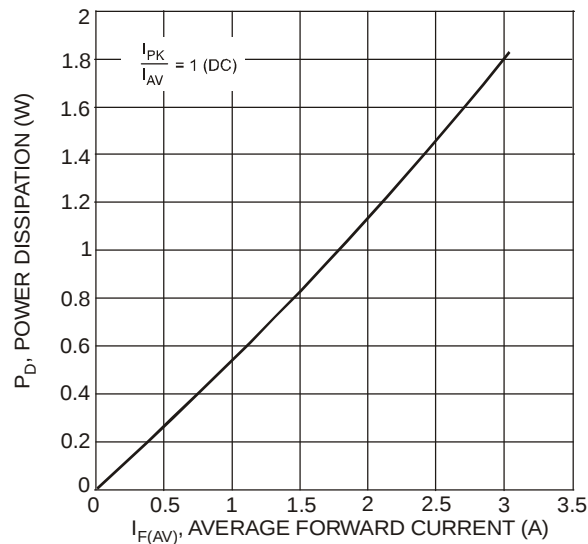
Thermal Characteristics

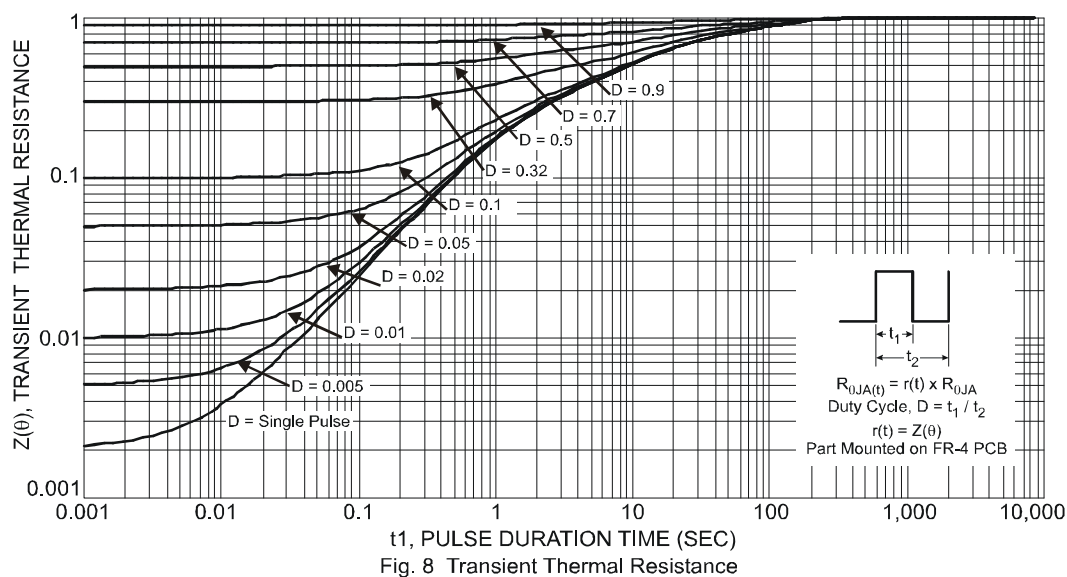
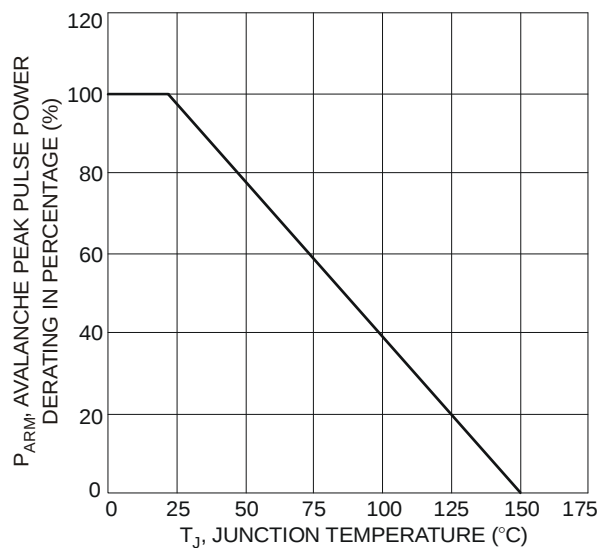
Characteristic	Symbol	Typ	Max	Unit
Thermal Resistance Junction to Soldering (Note 3)	R _{θJS}	—	7	°C/W
Thermal Resistance Junction to Ambient (Note 4) T _A = 25°C	R _{θJA}	125	—	
Thermal Resistance Junction to Case (Note 4) T _A = 25°C	R _{θJC}	21	—	
Operating and Storage Temperature Range	T _J , T _{STG}	-55 to +175		°C

Electrical Characteristics @T_A = 25°C unless otherwise specified

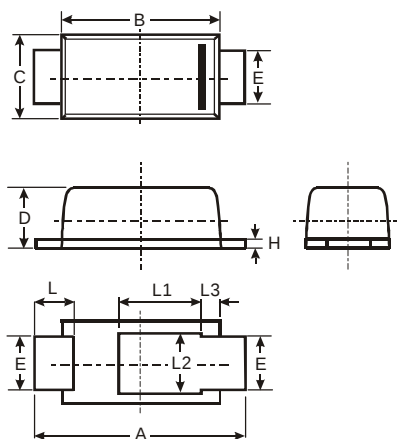
Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Reverse Breakdown Voltage (Note 5)	V _{(BR)R}	100	—	—	V	I _R = 1μA
Forward Voltage	V _F	—	—	0.77	V	I _F = 1.0A, T _A = 25°C
		—	0.58	0.62		I _F = 1.0A, T _A = 125°C
		—	—	0.86		I _F = 2.0A, T _A = 25°C
		—	0.65	0.7		I _F = 2.0A, T _A = 125°C
Leakage Current (Note 5)	I _R	—	—	1	μA	V _R = 100V, T _A = 25°C
		—	0.2	0.5	mA	V _R = 100V, T _A = 125°C
Total Capacitance	C _T	—	36	—	pF	V _R = 5V _{DC} , f = 1MHz

- Notes:
3. Theoretical R_{θJS} calculated from the top center of the die straight down to the PCB/cathode tab solder junction.
 4. Part mounted on FR-4 board with 2 oz., minimum recommended copper pad layout, which can be found on our website at <http://www.diodes.com>.
 5. Short duration pulse test used to minimize self-heating effect.





Package Outline Dimensions



POWERDI [®] 123			
Dim	Min	Max	Typ
A	3.50	3.90	3.70
B	2.60	3.00	2.80
C	1.63	1.93	1.78
D	0.93	1.00	0.98
E	0.85	1.25	1.00
H	0.15	0.25	0.20
L	0.40	0.50	0.45
L1	-	-	1.35
L2	-	-	1.10
L3	-	-	0.20
All Dimensions in mm			

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DFLS1100

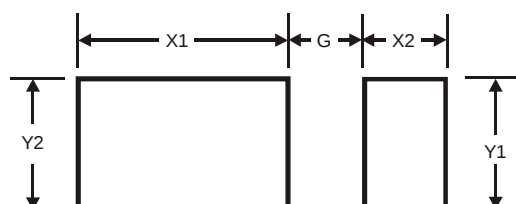
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Suggested Pad Layout



Dimensions	Value (in mm)
G	1.0
X1	2.2
X2	0.9
Y1	1.4
Y2	1.4

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